



Chipsmall Limited consists of a professional team with an average of over 10 year of expertise in the distribution of electronic components. Based in Hongkong, we have already established firm and mutual-benefit business relationships with customers from,Europe,America and south Asia,supplying obsolete and hard-to-find components to meet their specific needs.

With the principle of “Quality Parts,Customers Priority,Honest Operation,and Considerate Service”,our business mainly focus on the distribution of electronic components. Line cards we deal with include Microchip,ALPS,ROHM,Xilinx,Pulse,ON,Everlight and Freescale. Main products comprise IC,Modules,Potentiometer,IC Socket,Relay,Connector.Our parts cover such applications as commercial,industrial, and automotives areas.

We are looking forward to setting up business relationship with you and hope to provide you with the best service and solution. Let us make a better world for our industry!



Contact us

Tel: +86-755-8981 8866 Fax: +86-755-8427 6832

Email & Skype: info@chipsmall.com Web: www.chipsmall.com

Address: A1208, Overseas Decoration Building, #122 Zhenhua RD., Futian, Shenzhen, China



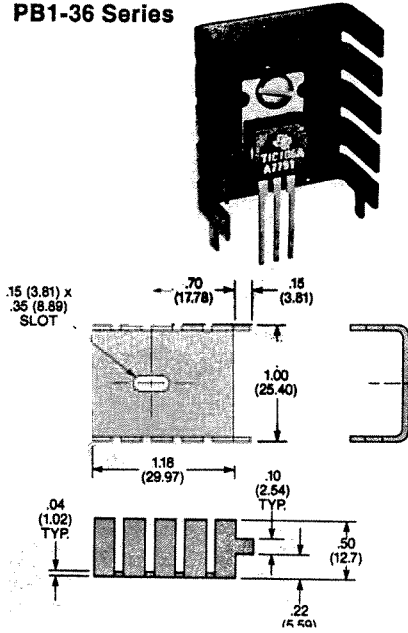
SECTION 2

HEAT DISSIPATORS FOR PLASTIC CASE, CASE-MOUNTED SEMICONDUCTORS

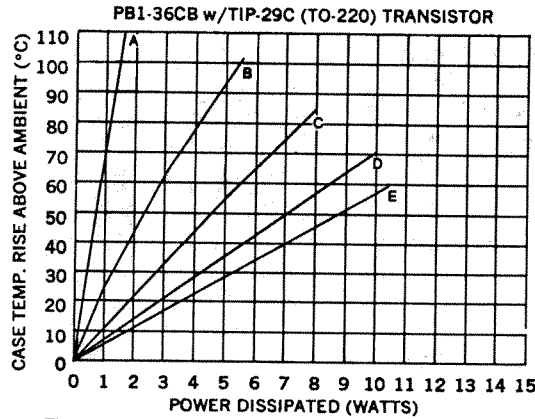
Vertically mounted heat dissipators with board mounting tabs

- Permits higher power levels or lower operating temperatures while occupying a minimum of valuable board space.
- Allows back-to-back dual mounting for thermal matching applications.
- Bendable tabs simplify installation to the circuit board — no mounting hardware or special tools required.
- Dissipators are available with nickel or tin finishes — allows heat sink mounting tabs to be flow-soldered onto board along with other components.
- Each dissipator is optimally designed for maximum effective surface area in a minimum working envelope.

PB1-36 Series



Dimensions are for reference use only. Contact IERC for dimensions with tolerances or standard part drawings.



DESCRIPTION OF CURVES
 A. N.C. Horiz. Device Only Freestanding.
 B. N.C. Horiz. & Vert. With Dissipator.
 C. 200 FPM w/Diss.
 D. 500 FPM w/Diss.
 E. 1000 FPM w/Diss.

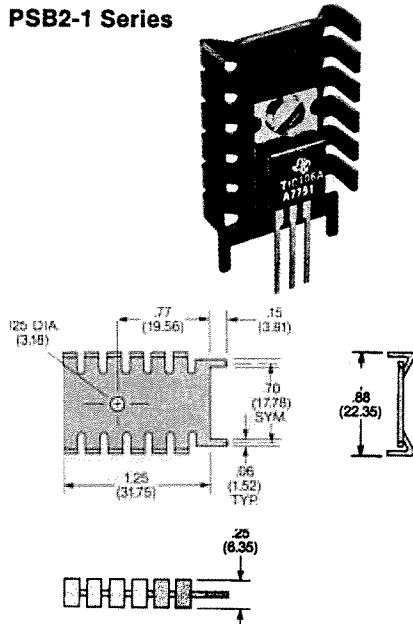
- Thermal Resistance Case to Sink is 0.9-1.1 °C/W w/Joint Compound.
- Derate 2.4 °C/watt for unplated part in natural convection only.

Ordering Information

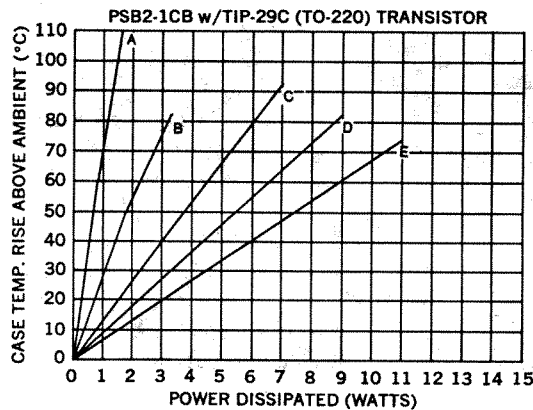
IERC PART NO.					Semiconductor Accommodated	Max. Weight (Grams)
Unplated	Comm'l. Black Anodize	Mil. Black Anodize	Solderable Plating			
			Nickel	Tin		
PB1-36U	PB1-36CB	PB1-36B	PB1-36ND	PB1-36T	TO-126, TO-127, TO-220	3.9

Note: See page iv for other finishes.

PSB2-1 Series



Dimensions are for reference use only. Contact IERC for dimensions with tolerances or standard part drawings.



DESCRIPTION OF CURVES
 A. N.C. Horiz. Device Only Freestanding.
 B. N.C. Horiz. & Vert. With Dissipator.
 C. 200 FPM w/Diss.
 D. 500 FPM w/Diss.
 E. 1000 FPM w/Diss.

- Thermal Resistance Case to Sink is 0.9-1.1 °C/W w/Joint Compound.
- Derate 3.5 °C/watt for unplated part in natural convection only.

Ordering Information

IERC PART NO.					Semiconductor Accommodated	Max. Weight (Grams)
Unplated	Comm'l. Black Anodize	Mil. Black Anodize	Solderable Plating			
			Nickel	Tin		
PSB2-1U	PSB2-1CB	PSB2-1B	PSB2-1ND	PSB2-1T	TO-126, TO-127, TO-220	2.4

Note: See page iv for other finishes.